

CORRECTED VERSION

(19) World Intellectual Property Organization
International Bureau



162162

(43) International Publication Date
10 October 2002 (10.10.2002)

PCT

(10) International Publication Number
WO 02/079542 A3

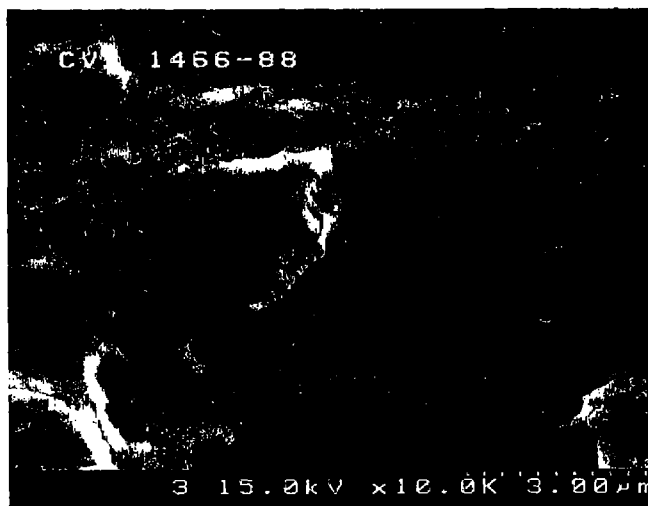
- (51) International Patent Classification⁷: H05K 3/38 KOCHILLA, John, R.; 4211 West 11th Street, Cleveland, OH 44109 (US).
- (21) International Application Number: PCT/IB01/02901
- (22) International Filing Date: 23 July 2001 (23.07.2001)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:
09/628,036 27 July 2000 (27.07.2000) US
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- (81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZW.
- (84) Designated States (regional): European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR).
- Published:
— with international search report
- (88) Date of publication of the international search report:
6 February 2003

[Continued on next page]

(54) Title: IMPROVED ADHESION OF POLYMERIC MATERIALS TO METAL SURFACES



G00002



(57) Abstract: The present invention relates to a process for treating a metal substrate to improve adhesion of polymeric materials thereto, comprising the steps of intergranular etching a surface of the metal substrate; and applying an immersion plated metal to the intergranular etched surface by immersing the surface in an immersion plating composition comprising one or more plating metals selected from tin, silver, bismuth, copper, nickel, gallium and germanium. In one embodiment, the immersion plated metal is tin. In one embodiment, the process further comprises a step of adhering the immersion metal plated surface to a surface of a polymeric non-conductive material. In another embodiment, the polymeric nonconductive material is one or more of PTFE, an epoxy resin, a polyimide, a polycyanate ester, a butadiene terephthalate resin, or mixtures thereof. In one embodiment, the process further comprises a step of applying a silane over the immersion plated metal from an aqueous solution of a silane.

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(48) Date of publication of this corrected version:

20 March 2003

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.***(15) Information about Correction:**

see PCT Gazette No. 12/2003 of 20 March 2003, Section II